

**Harvatek Surface Mount LED Data Sheet
HT-V116UYG-2916**

Official Product	HT-V116UYG-2916	Customer Part No.		Data Sheet No.
Preliminary Product	*****	*****		HT-V116UYG-2916
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DISCLAIMER

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HARVATEK's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of HARVATEK or HARVATEK INTERNATIONAL. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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Product Specifications

	Specification	Material	Quantity
I _v	36mcd minimum @20mA / T _a =25° C, ± 10%		
λ _D	573nm @20mA / T _a =25° C, ± 0.5nm		
V _F	2.4V maximum @20mA / T _a =25°C, ± 0.05 V		
I _R	≤1μA @ V _R =5V		
MSL	2		
Resin	Clear	Epoxy resin	
Carrier tape	Per EIA 481-1A specs	Plastic tape	2000pcs per reel
Reel	Per EIA 481-1A specs	Plastic white	
Label	HT standard	Paper	
Packing bag	220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	HT standard	Paper	

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of I_v, λ_D and V_f. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

ATTENTION: Electrostatic Discharge (ESD) protection




The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. ESD precaution must be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

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Label Specifications

HARVATEK			Date: yyyy/mm/dd
CUSTOMER P/N: 			
HARVATEK P/N: 		QTY: PCS 	
LOT NO: 		QC	
IV BIN:	COLOR BIN:	VF:	

 Customer P/N: To Be Defined

 Harvatek P/N:

H T - V 1 1 6 UYG - 2 9 1 6



Series Name	Emitting Color	Customer Code
HT-V116 HT: Harvatek V116: 0.6mm side-emitting series with zener diode 3.2(L) x 1.1(W) x 0.6(H) mm	UYG AlInGaP Yellow Green @ 20mA	2916 Customer Product Code

 Lot No.:

1 2 3 4 5 6 7 8 9 10
P 1 2 2 3 0 A - C T

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Code 1	Code 2	Code 3	Code 4, 5	Code 6, 7	Code 9	Code 10
	Mfg. Year	Mfg. Month	Mfg. Date	Lots	Resin Color	Packaging
Internal Tracing Code	Z: 2000 1: 2001 2: 2002 3: 2003	1: Jan. 9: Sep. A: Oct. B: Nov. C: Dec.	1~31/ (30)	01~99, A,B,C...	D: Diffused	T: Tape & Reel

Luminous Intensity (Iv) Bin:

Color	Bin Code	Spec. Range
Amber	P	45.0-71.5 mcd
	Q	71.5-112.5mcd

Forward Voltage (Vf) Bin:

Color	Bin Code	Spec. Range
Amber	-	2.4V max

Dominant Wavelength Bin (λ_D) Bin:

Color	Bin Code	Spec. Range
Amber	C	567.5-570.5 mcd
	D	570.5-573.5mcd
	E	573.5-576.5mcd

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Product Features:

Electro-Optical Characteristics

(I_F @ 20mA, $T_a = 25^\circ\text{C}$)

Code for parts	Lighting Color	Material	$V_F(\text{V})$		$\lambda(\text{nm})$			$I_V(\text{mcd})$
			typ	max	λ_D	λ_P	$\Delta\lambda$	Typ
HT-V116UYG	Yellow Green	AlInGaP	1.9	2.4	573	574	20	70

Package Outline Dimension and Recommended Soldering Pattern for Reflow Soldering

Unit: mm Tolerance: ± 0.1

Outline Dimension	Soldering Pattern
Soldering terminals may shift in the x, y direction.	

Absolute Maximum Ratings

($T_a = 25^\circ\text{C}$)

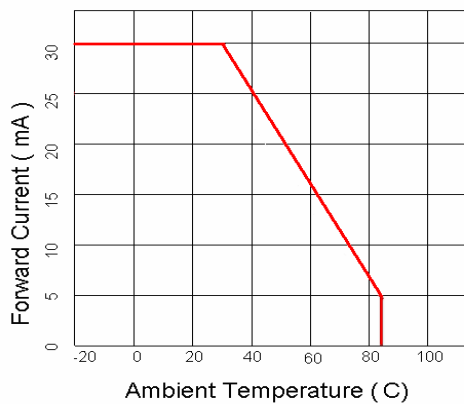
Series	P_d (mW)	I_F (mA)	I_{FP} (mA)	V_R (V)	I_R (uA)	T_{OP} ($^\circ\text{C}$)	T_{ST} ($^\circ\text{C}$)
HT-V116UYG	72	30	100**	5	≤ 1 @ $V_R = 5\text{V}$	-40~+100	-40~+100

** Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width

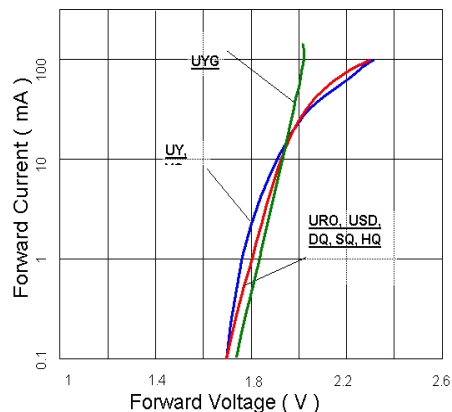
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Characteristics Curves

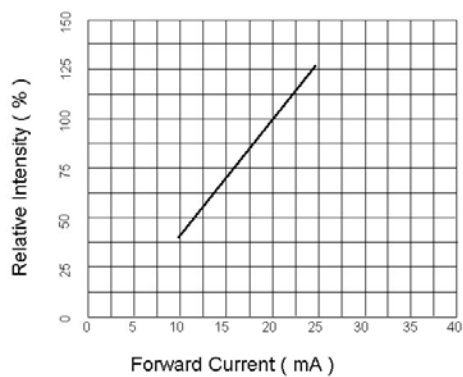
Forward Current vs. Ambient Temperature



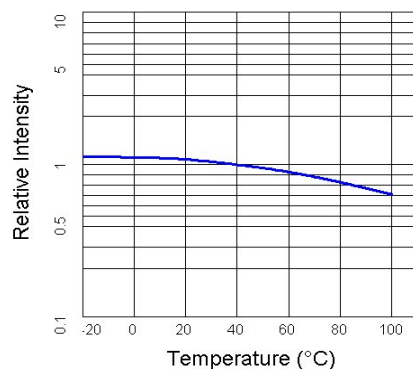
Forward Voltage vs. Forward Current



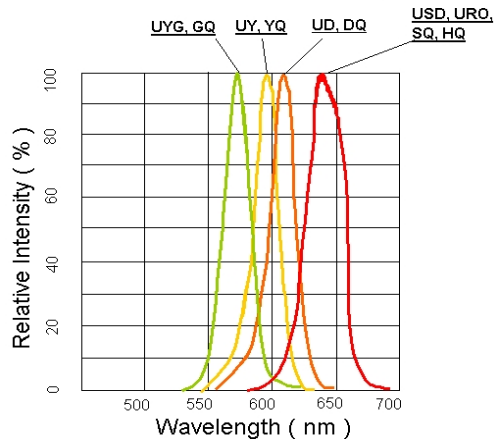
Relative Intensity vs. Forward Current



Relative Intensity vs. Ambient Temperature
Pulsed 20mA; 300us pulse, 10ms period



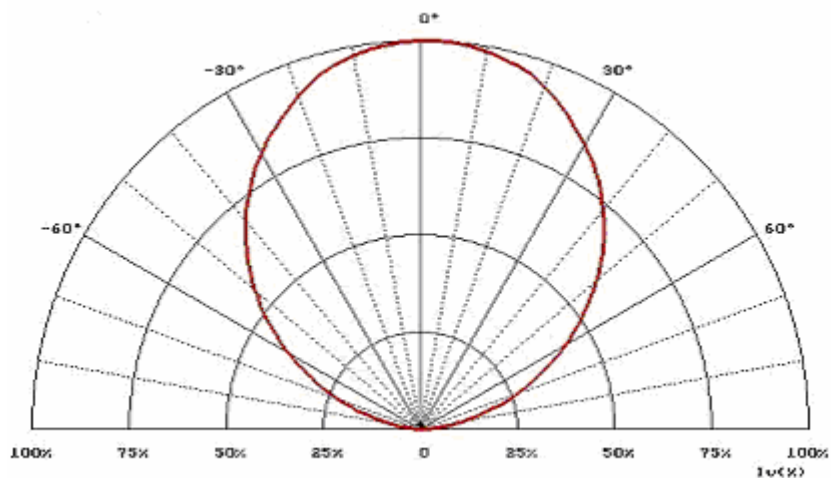
Relative Intensity vs. Wavelength



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Radiation Pattern

Directive Characteristics



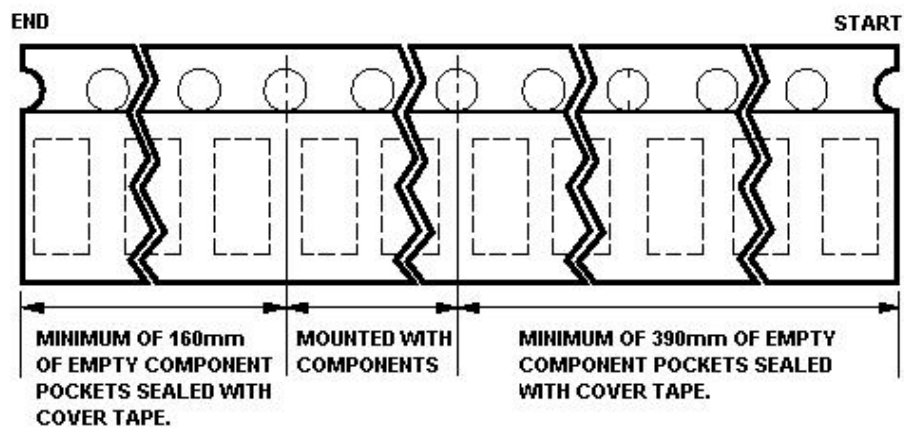
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Packaging

Tape Dimension

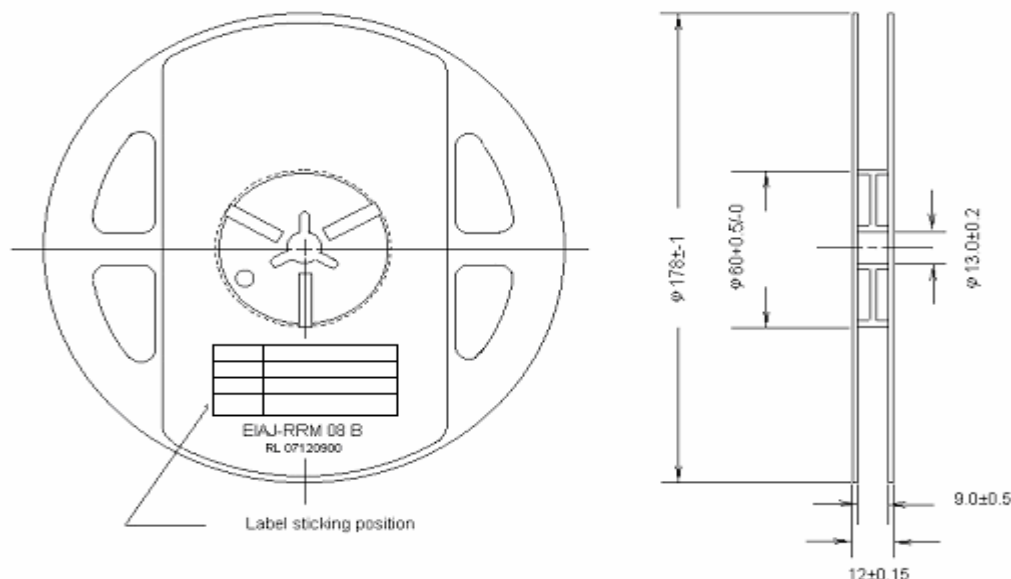
Part No.	Dim. A	Dim. B	Dim. C	Q'ty/Reel
HT-V116	-	-	-	2K

Unit: mm

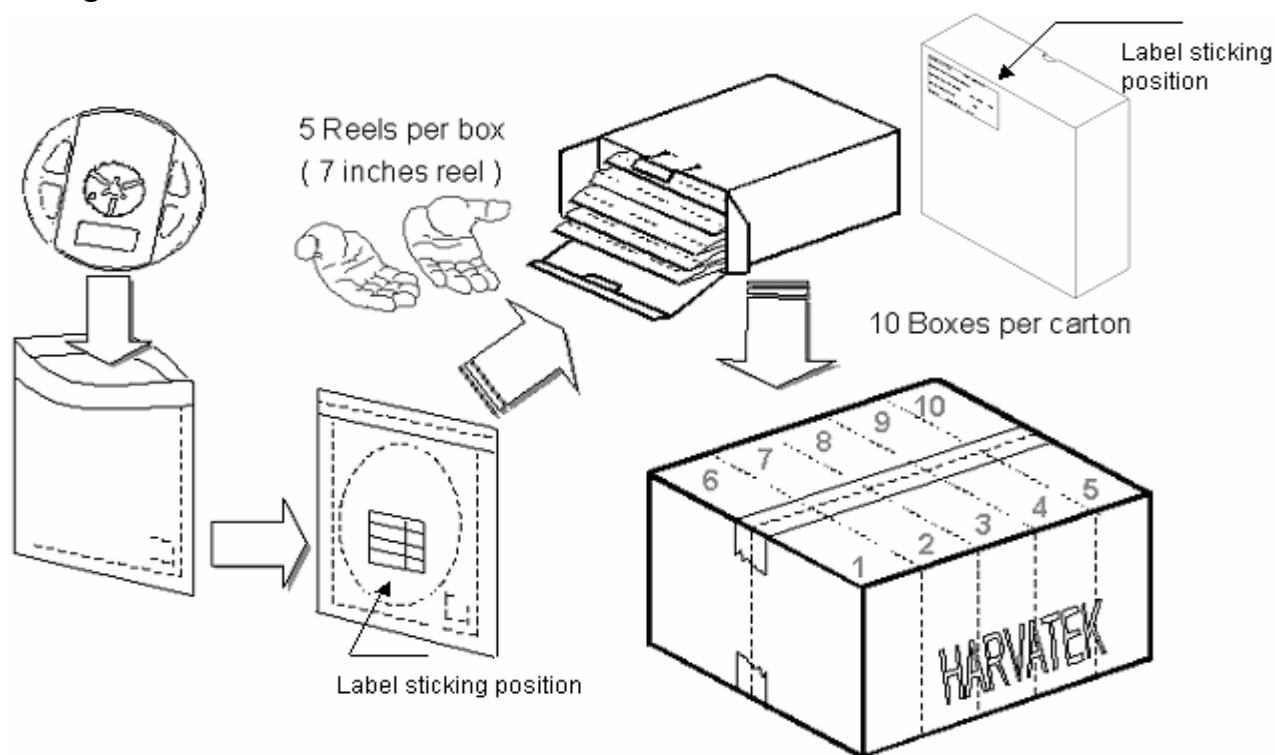


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Reel Dimension



Packing



5 boxes per carton is available depending on shipment quantity.

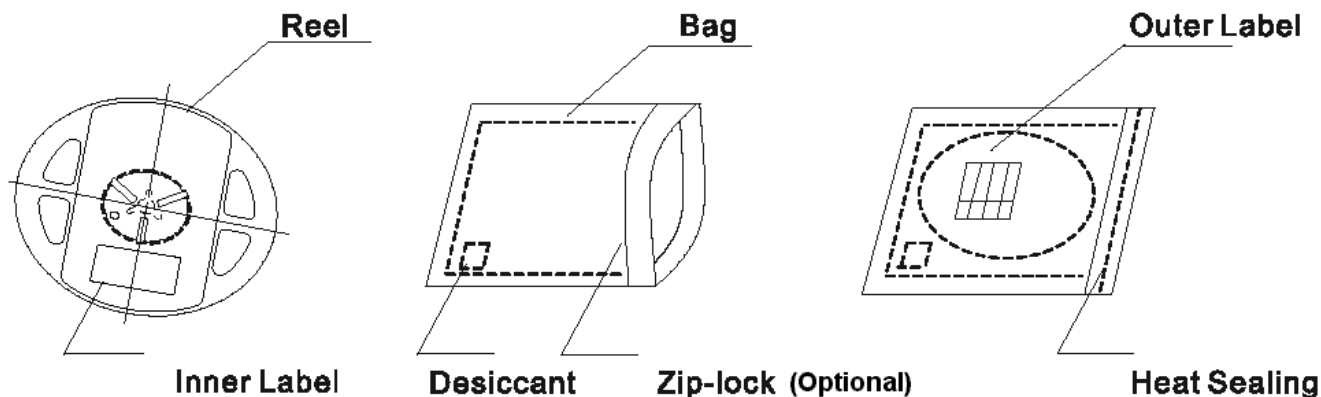
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Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



PRECAUTIONS

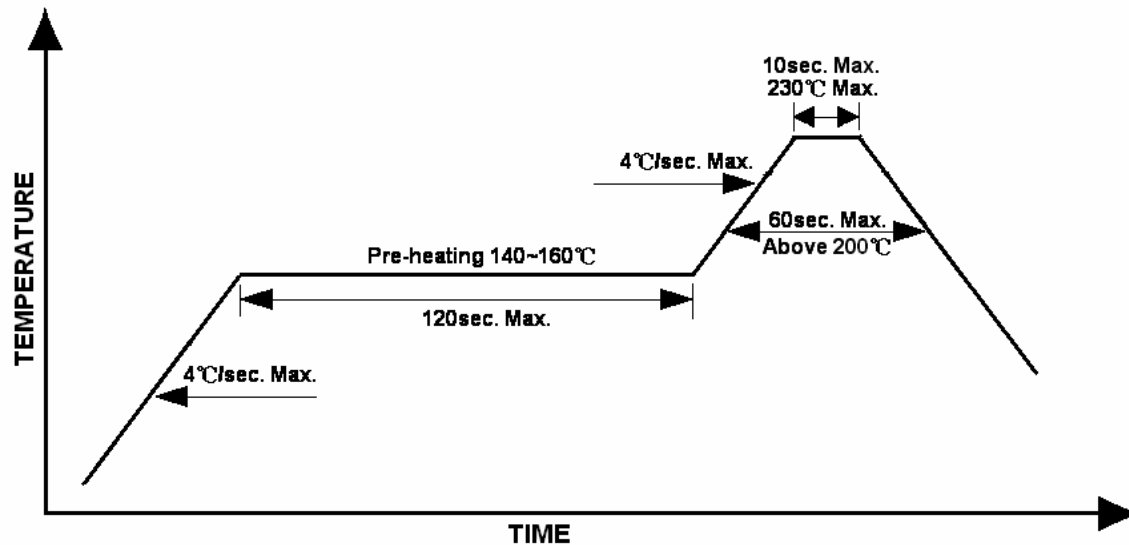
1. Avoid exposure to moisture at all times during transportation or storage.
2. Anti-Static precaution must be taken when handling GaN, InGaN, and AlInGaP products.
3. It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage beyond the specified limit.
4. Avoid operation beyond the limits as specified by the absolute maximum ratings.
5. Avoid direct contact with the surface through which the LED emits light.
6. If possible, assemble the unit in a clean room or dust-free environment.

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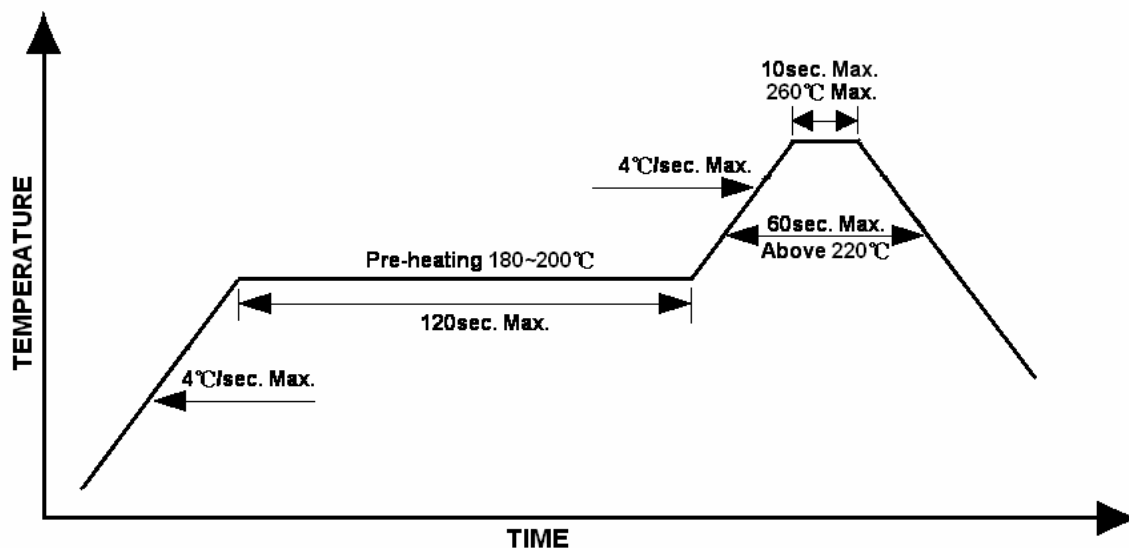
Reflow Soldering

- Recommended tin glue specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

Lead Solder Profile



Lead-free Solder Profile



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Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electric-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

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Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial release for stamp-off 2916		1.0	12-22-2005

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